

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor: Sukharev, Catabay, Lu
Title: Interconnect Integration
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Attorney docket: 02-6392/1D
Customer number: **24,319**

INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. § 1.97

Mail Stop Patent Application
Commissioner for Patents
P.O. Box 1450
Alexandria VA 22313-1450

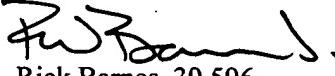
Sir:

In compliance with 37 C.F.R. §§ 1.97 and 1.98, applicants provide this Information Disclosure Statement and accompanying form PTO-1449, listing the citations of references to be considered in the above referenced case. By this submission applicants are not admitting the materiality of these citations; they are merely submitted to ensure full compliance with 37 C.F.R. § 1.56.

This application relies on prior pending U.S. patent application serial number 10/448,082 filed 2003.05.29 for an earlier effective filing date under 35 USC § 120. Therefore, copies of these references are not provided herewith, as permissible under 37 CFR § 1.98(d). These references were either cited in the Information Disclosure Statement filed in the prior pending application, or were cited by the examiner in the prior pending application.

Sincerely,

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2004.03.17
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FORM PTO-1449 INFORMATION DISCLOSURE CITATIONS IN AN APPLICATION	Atty Docket:	02-6392/1D	Serial #:
	Applicant:	Sukharev, Catabay, Lu	
	Filing Date:	2004.03.17	Group:

U.S. PATENT DOCUMENTS

Examiner Initial	Cite #	Document Number	Date	Name	Class	Sub-Class	Filing Date
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FOREIGN PATENT DOCUMENTS

Examiner Initial	Cite #	Document Number	Date	Country	Class	Sub-Class	Translation
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OTHER NON-PATENT DOCUMENTS

Examiner Initial	Cite #	Author, title, date, pertinent pages, etc.
	1	Hu et al., <i>Chemical vapor deposition copper interconnections and electromigration</i> , Electrochemical Society Proceedings, 97-25, 1514 (1997).
	2	Hu et al., Applied Physics Letters, Vol. 74, Number 20, pp. 2945-2947 (1999).
	3	Wang et al., <i>Stress-free polishing advances copper integration with ultralow-k dielectrics</i> , Solid State Technology, pp. 101-106, October 2001.

Examiner	Date Considered:
EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.	

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